

Features

- Frequency range : 16MHz to 66MHz
- Ceramic SMD package
- Seam sealing
- External dimensions (mm)
L : 2.0 x W : 1.6 x H : 0.5
- RoHS compliant & Pb free

Applications

- Bluetooth, Wireless LAN
- Microprocessor
- Mobile phone, Computer, Modem
- Audio, Video
- Consumer products

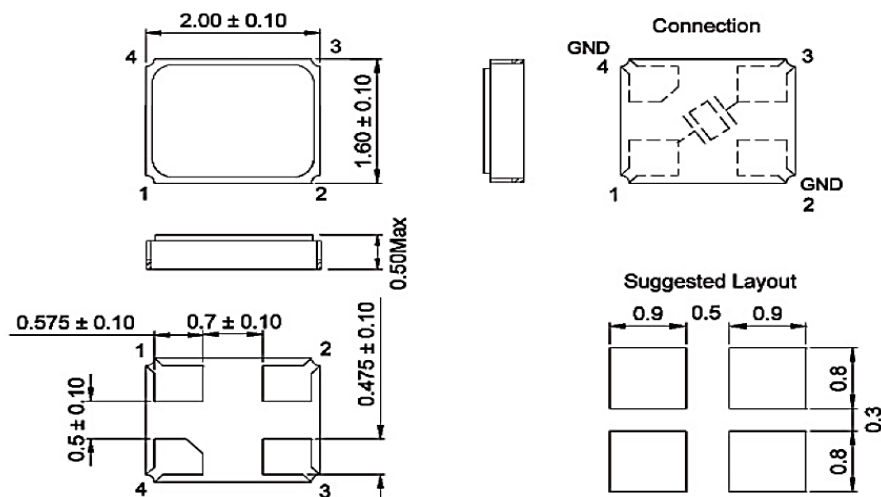
Electrical Characteristics

Item		8Y	Conditions
Frequency Range	F_0	16MHz ~ 66MHz	
Frequency Tolerance	F_{tol}	$\pm 30\text{ppm}$, $\pm 20\text{ppm}$, $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	$\pm 30\text{ ppm}$	-20°C ~ +70°C
		$\pm 20\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 10\text{ ppm}$	-30°C ~ +85°C
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
		$\pm 20\text{ ppm}$	
		$\pm 60\text{ ppm}$	-40°C ~ +125°C
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-30°C ~ +85°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 200μW (50μW Typ.)	
Load Capacitance	C_L	6pF, 7pF, 8pF, 9pF 10pF, 12pF, 16pF, 18pF	
Aging	F_{aging}	$\pm 3\text{ ppm Max.}$	at 25°C $\pm$ 3°C, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

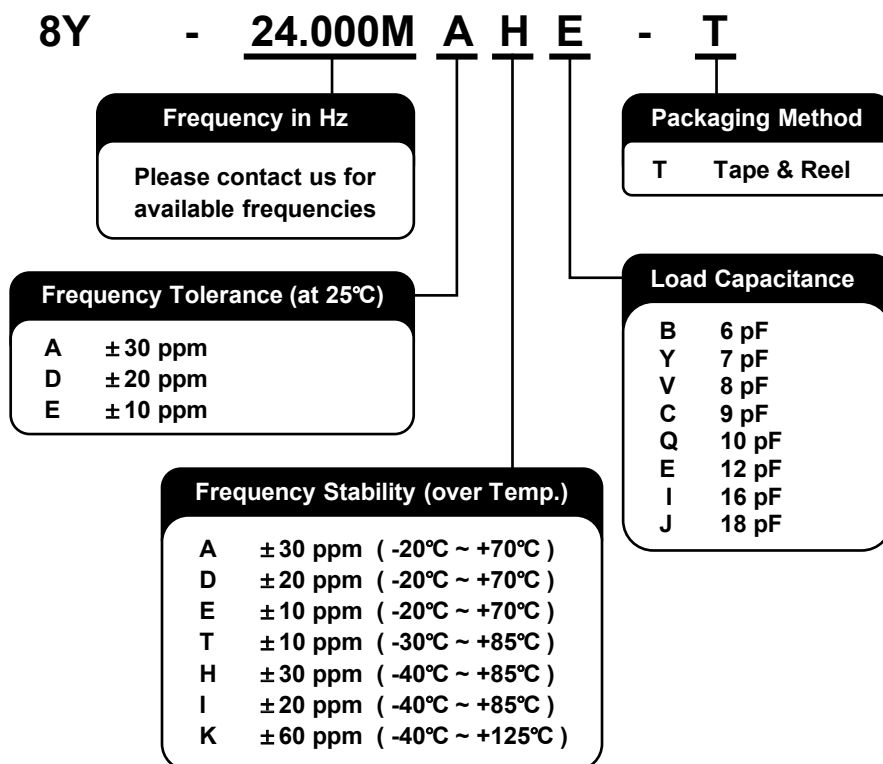
Motional Resistance (ESR)

Fundamental	
16 ~ 19.2 MHz	120Ω Max.
19.2 ~ 30 MHz	90Ω Max.
30 ~ 66 MHz	50Ω Max.

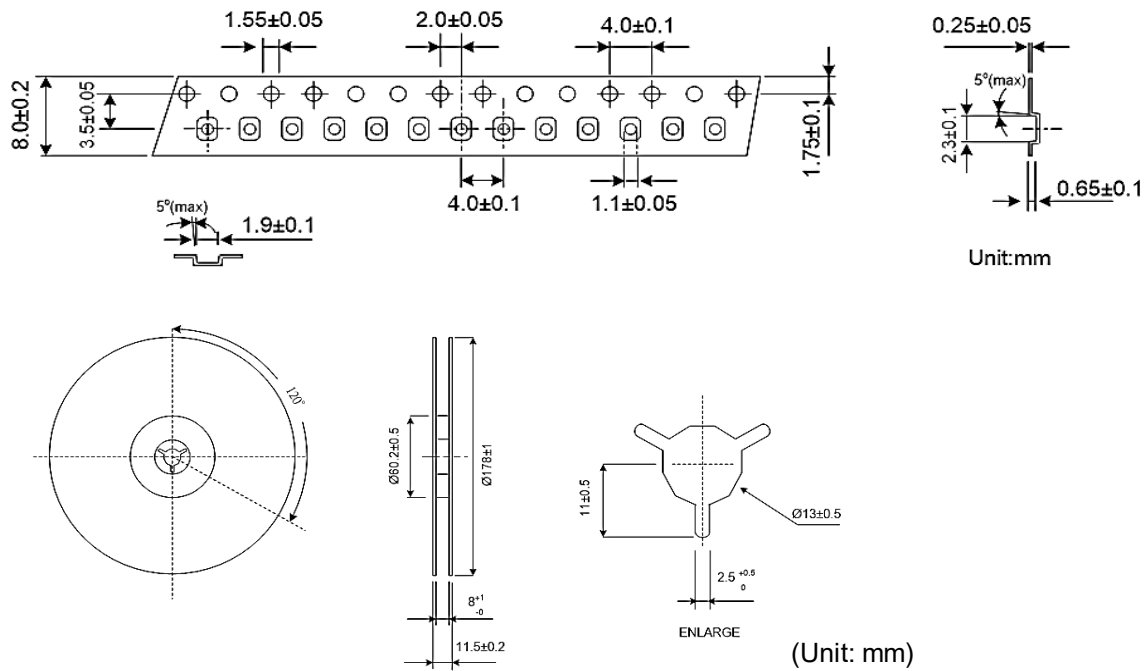
Dimensions



Ordering Information



Packing



Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

